

STARPOWER

SEMICONDUCTOR™

IGBT

GD100FFU120C6S

Preliminary

Molding Type Module**1200V/100A 6 in one-package**

General Description

STARPOWER IGBT Power Module provides ultra low conduction loss as well as short circuit ruggedness. They are designed for the applications such as general inverters and UPS.



Features

- $V_{CE(sat)}$ with positive temperature coefficient
- 10 μ s short circuit capability
- Rugged with ultrafast performance
- Square RBSOA
- Low inductance case
- Fast & soft reverse recovery anti-parallel FWD
- Isolated copper baseplate using DBC technology

Typical Applications

- Inverter for motor drive
- AC and DC servo drive amplifier
- Uninterruptible power supply

Absolute Maximum Ratings $T_C=25^\circ\text{C}$ unless otherwise noted

Symbol	Description	GD100FFU120C6S	Units
V_{CES}	Collector-Emitter Voltage	1200	V
V_{GES}	Gate-Emitter Voltage	± 20	V
I_C	Collector Current @ $T_C=25^\circ\text{C}$ @ $T_C=80^\circ\text{C}$	150 100	A
$I_{CM(1)}$	Pulsed Collector Current @ $T_C=80^\circ\text{C}$	200	A
I_F	Diode Continuous Forward Current	100	A
I_{FM}	Diode Maximum Forward Current	200	A
P_D	Maximum power Dissipation @ $T_j=150^\circ\text{C}$	868	W
T_{SC}	Short Circuit Withstand Time @ $T_j=150^\circ\text{C}$	10	μs
T_j	Maximum Junction Temperature	150	$^\circ\text{C}$
T_{STG}	Storage Temperature Range	-40 to +125	$^\circ\text{C}$
V_{ISO}	Isolation Voltage RMS, $f=50\text{Hz}$, $t=1\text{min}$	2500	V
Mounting Torque	Mounting Screw: M5	3.0 to 6.0	N.m

Notes:

(1) Repetitive rating: Pulse width limited by max. junction temperature

Electrical Characteristics of IGBT $T_C=25^\circ\text{C}$ unless otherwise noted**Off Characteristics**

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
$V_{(BR)CES}$	Collector-Emitter Breakdown Voltage	$T_j=25^\circ\text{C}$	1200			V
I_{CES}	Collector Cut-Off Current	$V_{CE}=V_{CES}$, $V_{GE}=0\text{V}$, $T_j=25^\circ\text{C}$			5.0	mA
I_{GES}	Gate-Emitter Leakage Current	$V_{GE}=V_{GES}$, $V_{CE}=0\text{V}$, $T_j=25^\circ\text{C}$			400	nA

On Characteristics

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
$V_{GE(th)}$	Gate-Emitter Threshold Voltage	$I_C=1.0\text{mA}$, $V_{CE}=V_{GE}$, $T_j=25^\circ\text{C}$	4.4	5.0	6.0	V
$V_{CE(sat)}$	Collector to Emitter Saturation Voltage	$I_C=100\text{A}$, $V_{GE}=15\text{V}$, $T_j=25^\circ\text{C}$		3.45	3.90	V
		$I_C=100\text{A}$, $V_{GE}=15\text{V}$, $T_j=125^\circ\text{C}$		3.75		

Switching Characteristics

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
$t_{d(on)}$	Turn-On Delay Time	$V_{CC}=600V, I_C=100A,$ $R_G=5.6\Omega, V_{GE}=\pm 15V,$ $T_J=25^\circ C$		310		ns
t_r	Rise Time			64		ns
$t_{d(off)}$	Turn-Off Delay Time			350		ns
t_f	Fall Time			105		ns
E_{on}	Turn-On Switching Loss			4.76		mJ
E_{off}	Turn-Off Switching Loss			4.25		mJ
$t_{d(on)}$	Turn-On Delay Time	$V_{CC}=600V, I_C=100A,$ $R_G=5.6\Omega, V_{GE}=\pm 15V,$ $T_J=125^\circ C$		328		ns
t_r	Rise Time			65		ns
$t_{d(off)}$	Turn-Off Delay Time			350		ns
t_f	Fall Time			132		ns
E_{on}	Turn-On Switching Loss			7.20		mJ
E_{off}	Turn-Off Switching Loss			5.50		mJ
C_{ies}	Input Capacitance	$V_{CE}=25V, f=1MHz,$ $V_{GE}=0V$		4.30		nF
C_{oes}	Output Capacitance			0.40		nF
C_{res}	Reverse Transfer Capacitance			0.16		nF
I_{SC}	SC Data	$T_P \leq 10\mu s, V_{GE}=15V,$ $T_J=125^\circ C, V_{CC}=900V,$ $V_{CEM} \leq 1200V$		TBD		A
L_{CE}	Stray Inductance			21		nH
$R_{CC'+EE'}$	Module Lead Resistance, Terminal To Chip			1.80		m Ω

Electrical Characteristics of DIODE $T_C=25^\circ C$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
V_F	Diode Forward Voltage	$I_F=100A$	$T_J=25^\circ C$	2.05	2.45	V
			$T_J=125^\circ C$	1.95		
Q_r	Recovered charge	$I_F=100A,$	$T_J=25^\circ C$	5.4		μC
			$T_J=125^\circ C$	11.2		
I_{RM}	Peak Reverse Recovery Current	$V_R=600V,$ $di/dt=-1950A/\mu s,$	$T_J=25^\circ C$	81		A
			$T_J=125^\circ C$	101		
E_{rec}	Reverse Recovery Energy	$V_{GE}=-15V$	$T_J=25^\circ C$	3.54		mJ
			$T_J=125^\circ C$	6.57		

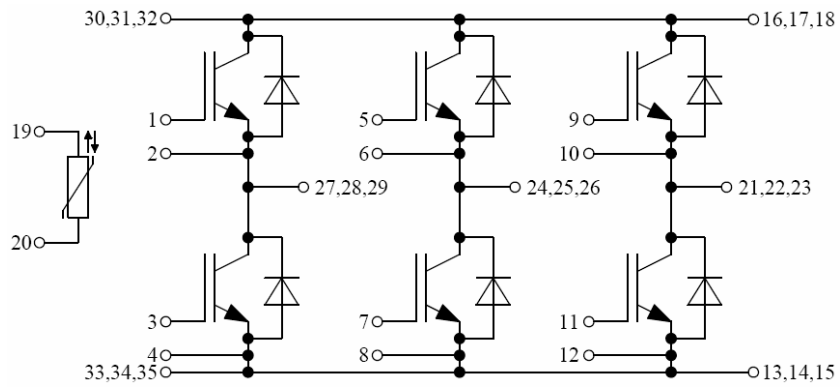
Electrical Characteristics of NTC $T_C=25^{\circ}\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
R_{25}	Rated Resistance			5.0		k Ω
$\Delta R/R$	Deviation of R_{100}	$R_{100}=493.3\Omega$	-5		5	%
P_{25}	Power Dissipation				20.0	mW
$B_{25/50}$	B-value	$R_2=R_{25}\exp[B_{25/50}(1/T_2-1/(298.15\text{K}))]$		3375		K

Thermal Characteristics

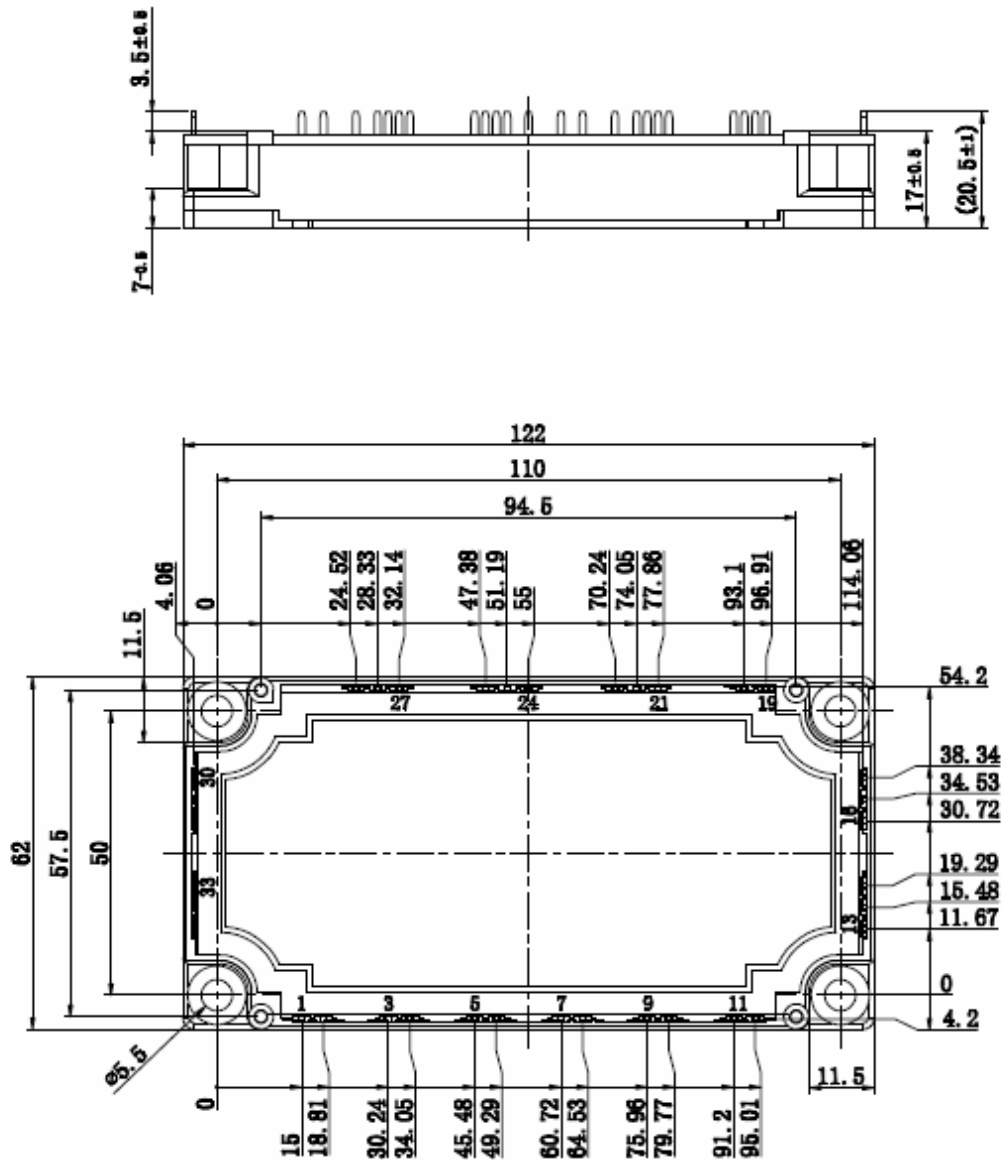
Symbol	Parameter	Typ.	Max.	Units
$R_{\theta JC}$	Junction-to-Case (per IGBT)		0.144	K/W
$R_{\theta JC}$	Junction-to-Case (per DIODE)		0.230	K/W
$R_{\theta CS}$	Case-to-Sink (Conductive grease applied)	0.009		K/W
Weight	Weight of Module	300		g

Equivalent Circuit Schematic



Package Dimension

Dimensions in Millimeters



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